



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-07-21
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	LAURENT TOSI	<b>Representative Title</b>	MMS MD CHAMPION
<b>Representative Phone *</b>	33 442 685 795	<b>Representative Email *</b>	<a href="mailto:laurent.tosi@st.com">laurent.tosi@st.com</a>
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST7FLITE05Y0M6	P1Q7*819XXX3	A	9998	2014-07-21
	Amount	UoM	Unit type	ST ECOPACK Grade
	150.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SON	JEDEC	16	L bend	
Comment	Package: SO 16 .15 TO JEDEC MS-012			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	P1Q7*819XX3					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	6.361	mg	supplier	die	Silicon (Si)	7440-21-3		6.332	mg	995441	42213
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	786	33
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.006	mg	943	40
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.018	mg	2830	120
LEADFRAME	Other inorganic materials	62.013	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		59.664	mg	962121	397760
LEADFRAME				supplier	ALLOY	Iron (Fe)	7439-89-6		1.439	mg	23205	9593
LEADFRAME				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.073	mg	1177	487
LEADFRAME				supplier	ALLOY	Phosphorus (P)	7723-14-0		0.018	mg	290	120
LEADFRAME				supplier	COATING	Silver(Ag)	7440-22-4		0.819	mg	13207	5460
DIE ATTACH	Other inorganic materials	1.842	mg	supplier	GLUE	Epoxy resin A	9003-36-5		0.129	mg	70033	860
DIE ATTACH				supplier	GLUE	Epoxy resin B	68475-94-5		0.074	mg	40174	493
DIE ATTACH				supplier	GLUE	Silver(Ag)	7440-22-4		1.417	mg	769273	9447
DIE ATTACH				supplier	GLUE	Lactone	96-48-0		0.074	mg	40174	493
DIE ATTACH				supplier	GLUE	Polyoxypropylenediamine	9046-10-0		0.074	mg	40174	493
DIE ATTACH				supplier	GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	Trade secret		0.074	mg	40174	493
BONDING WIRE	Other inorganic materials	0.309	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.309	mg	1000000	2060
ENCAPSULATION	Other inorganic materials	76.746	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Trade secret		5.757	mg	75014	38380
ENCAPSULATION				supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		66.000	mg	859980	440000
ENCAPSULATION				supplier	MOLDING COMPOUND	Phenol Resin	Trade secret		3.070	mg	40002	20467
ENCAPSULATION				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.384	mg	5004	2560
ENCAPSULATION				supplier	MOLDING COMPOUND	Epoxy Cresol Novolac	29690-82-2		1.535	mg	20001	10233
FINISHING	Other inorganic materials	2.729	mg	supplier	CONNECTION COATING	Tin (Sn)	7440-31-5		2.729	mg	1000000	18193